Hi-Flow[®] II5-AC

Fiberglass-Reinforced, Phase Change Thermal Interface Material

Features and Benefits

- Thermal impedance: 0.37°C-in²/W (@25 psi)
- Can be applied directly to a cold heat sink
- One side adhesive-coated to aid in positioning
- · Fiberglass reinforced

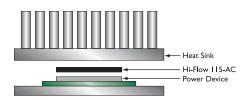


Bergquist Hi-Flow II5-AC is a thermally conductive fiber reinforced phase change material. The product consists of a thermally conductive 65°C phase change compound coated on a fiberglass web, and an adhesive coating on one side for attachment to a cold heat sink. There is no need to preheat the heat sink to apply the Hi-Flow II5-AC.

Hi-Flow 115-AC is designed as a thermal interface material between a computer processor and a heat sink. The pressure sensitive adhesive makes it simple to apply in high volume to heat sinks and the 65°C phase change temperature eliminates shipping and handling problems.

Hi-Flow 115-AC requires no protective liner for shipping or handling. The Hi-Flow coating has excellent handling characteristics at room temperature, and can withstand the handling and shipping process without protection.

Hi-Flow 115-AC handles like a Sil Pad at room temperature and flows like high-quality grease at elevated temperatures.



PROPERTY IMPERIAL VALUE METRIC VALUE TEST METHOD Color Gray Gray Visual Reinforcement Carrier Fiberglass Fiberglass — Thickness (inch) / (mm) 0.0055 0.139 ASTM D374 Elongation (%45° to Warp and Fill) 40 40 ASTM D882A Tensile Strength (psi) / (MPa) 900 6 ASTM D882A Continuous Use Temp (°F) / (°C) 302 150 — Phase Change Temp (°F) / (°C) 149 65 ASTM D3418 ELECTRICAL 300 300 ASTM D149 Dielectric Breakdown Voltage (Vac) 300 300 ASTM D150 Volume Resistivity (Ohm-meter) 1010 1010 ASTM D257 Flame Rating V-O V-O U.L. 94 THERMAL Thermal Conductivity (W/m-K) (1) 0.8 0.8 ASTM D5470	TYPICAL PROPERTIES OF HI-FLOW 115-AC							
Reinforcement Carrier Fiberglass Fiberglass - Thickness (inch) / (mm) 0.0055 0.139 ASTM D374 Elongation (%45° to Warp and Fill) 40 40 ASTM D882A Tensile Strength (psi) / (MPa) 900 6 ASTM D882A Continuous Use Temp (°F) / (°C) 302 I50 - Phase Change Temp (°F) / (°C) I49 65 ASTM D3418 ELECTRICAL Dielectric Breakdown Voltage (Vac) 300 300 ASTM D149 Dielectric Constant (1000 Hz) 3.5 3.5 ASTM D150 Volume Resistivity (Ohm-meter) Flame Rating V-O V-O U.L. 94 THERMAL Thermal Conductivity (W/m-K) (1) 0.8 ASTM D5470	PROPERTY	IMPERIAL VALUE		METRIC VALUE		TEST METHOD		
Thickness (inch) / (mm)	Color	Gray		Gray		Visual		
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Dielectric Breakdown Voltage (Vac) 300 300 ASTM D149 Dielectric Constant (1000 Hz) 3.5 3.5 ASTM D150 Volume Resistivity (Ohm-meter) 10 ¹⁰ 10 ¹⁰ ASTM D257 Flame Rating V-O V-O U.L. 94 THERMAL Thermal Conductivity (W/m-K) (1) 0.8 0.8 ASTM D5470	Phase Change Temp (°F) / (°C)	149		65		ASTM D3418		
Dielectric Constant (1000 Hz) 3.5 3.5 ASTM D150 Volume Resistivity (Ohm-meter) 10 ¹⁰ 10 ¹⁰ ASTM D257 Flame Rating V-O V-O U.L. 94 THERMAL Thermal Conductivity (W/m-K) (1) 0.8 0.8 ASTM D5470	ELECTRICAL							
Volume Resistivity (Ohm-meter) 10 ¹⁰ 10 ¹⁰ ASTM D257 Flame Rating V-O V-O U.L. 94 THERMAL Thermal Conductivity (W/m-K) (1) 0.8 0.8 ASTM D5470	Dielectric Breakdown Voltage (Vac)	300		300		ASTM D149		
Flame Rating V-O V-O U.L. 94 THERMAL Thermal Conductivity (W/m-K) (1) 0.8 0.8 ASTM D5470	Dielectric Constant (1000 Hz)	3.5		3.5		ASTM D150		
THERMAL Thermal Conductivity (W/m-K) (I) 0.8 0.8 ASTM D5470	Volume Resistivity (Ohm-meter)	1010		1010		ASTM D257		
Thermal Conductivity (W/m-K) (1) 0.8 0.8 ASTM D5470	Flame Rating	V-O		V-O		U.L. 94		
	THERMAL							
THERMAL PERFORMANCE vs PRESSURE	Thermal Conductivity (W/m-K) (I)	0.8		0.8		ASTM D5470		
	THERMAL PERFORMANCE vs PRESSURE							
Pressure (psi) 10 25 50 100 200	Press	sure (psi)	10	25	50	100	200	
TO-220 Thermal Performance (°C/W) 1.28 1.16 1.04 0.94 0.85	TO-220 Thermal Performance (°C/W)		1.28	1.16	1.04	0.94	0.85	
Thermal Impedance (°C-in²/W) (2) 0.44 0.37 0.35 0.27 0.15	Thermal Impedance (°C-in²/W) (2)		0.44	0.37	0.35	0.27	0.15	

I) This is the measured thermal conductivity of the Hi-Flow coating. It represents one conducting layer in a three-layer laminate. The Hi-Flow coatings are phase change compounds. These layers will respond to heat and pressure induced stresses. The overall conductivity of the material in post-phase change, thin film products is highly dependent upon the heat and pressure applied. This characteristic is not accounted for in ASTM D5470. Please contact Bergquist Product Management if additional specifications are required.

2) The ASTM D5470 (Bergquist modified) test fixture was used and the test sample was conditioned at 70°C prior to test. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

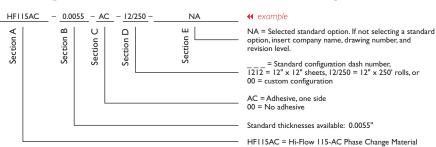
Typical Applications Include:

- Computer and peripherals
- As a thermal interface where bare die is exposed and needs to be heat sinked

Configurations Available:

- Sheet form, die-cut parts, and roll form
- With pressure sensitive adhesive

Building a Part Number



Note: To build a part number, visit our website at www.bergquistcompany.com.

Hi- Flow®: U.S. Patents 6,197,859 and 5,950,066



www.bergquistcompany.com

The Bergquist Company -North American Headquarters 18930 West 78th Street Chanhassen, MN 55317 Phone: 800-347-4572 Fax: 957-835-0430

The Bergquist Company - Europe Bramenberg 9a, 3755 BT Eemnes Netherlands Phone: 31-35-5380684 Fax: 31-35-5380295 The Bergquist Company - China Rm. 7C, Aihe Mansion No. 629 Ling Ling Road Shanghai, China 200030 Ph: 86-21-6464-2206 Fax: 86-21-6464-2709 All statements, technical information and recommendations herein are based on tests we believe to be reliable, and THE FOLLOWING IS MADE IN ILEU OF ALL WARRANTIES, EXPRESSED OR IMPLIED, INCLUDING THE IMPLIED WARRANTIES OF MARKETABILITY AND ITTINESS FOR PURPOSE. Sellers' and manufacturers' only obligation shall be to replace such quantity of the product proved to be defective. Before using user shall determine the suitability of the product for its intended use, and the user assumes all risks and liability whatsoever in connection therewith. NETHER SELLER NOR MANUFACTURER SHALL BE LIABLE EITHER INTORT OR IN CONTRACT FOR ANY LOSS OR DAMAGE DIRECT, INCIDENTAL, OR CONSEQUENTIAL, INCLUDING LOSS OF PROFITS OR REVENUE ARISING OUT OFTHE USE OR THE INABILITY TO USE A PRODUCT. No statement, purchase order or recommendations by seller or purchaser not contained herein shall have any force or effect unless in an agreement signed by the officers of the seller and manufacturer. PDS. 10084 I.F. LISAC 0,305

Standard Options